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# ***Optoelectronic Interconnects XIII***

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**Ray T. Chen**  
*Editors*

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# Contents

- vii *Conference Committee*
- ix Group IV photonics for the mid infrared (Plenary Paper) [8629-1]  
R. Soref, The Univ. of Massachusetts at Boston (United States)
- xxv Light in a twist: optical angular momentum (Plenary Paper) [8637-2]  
M. J. Padgett, Univ. of Glasgow (United Kingdom)

---

## SESSION 1 INTEGRATION TECHNOLOGIES I

---

- 8630 02 **Chip-to-board interconnects for high-performance computing (Invited Paper)** [8630-1]  
M. B. K. Riestler, Feldkirchnerstrasse (Austria); R. Houbertz-Krauss, S. Steenhusen, Fraunhofer  
Institute for Silicate Research ISC (Germany)
- 8630 03 **Performance methodologies of a modular miniature photonic turn connector** [8630-2]  
E. Childers, D. J. Hastings, D. Schoellner, A. Ugolini, J. Wakjira, US Conec, Ltd. (United States)
- 8630 04 **Development of low-cost polish-less optical multifiber backplane connector** [8630-3]  
T. Aoki, H. Muranaka, S. Aoki, Fujitsu Labs. Ltd. (Japan); K. Suematsu, M. Iwaya, M. Shiino,  
Furukawa Electric Co., Ltd. (Japan)
- 8630 05 **Graded-index core polymer optical waveguide circuit fabricated using a microdispenser  
for high-density on-board optical interconnects** [8630-4]  
K. Soma, T. Ishigure, Keio Univ. (Japan)
- 8630 06 **Active or passive fiber-chip-alignment: approaches to efficient solutions** [8630-5]  
G. Böttger, H. Schröder, R. Jordan, Fraunhofer-Institut für Zuverlässigkeit und  
Mikrointegration (Germany)

---

## SESSION 2 INTEGRATION TECHNOLOGIES II

---

- 8630 08 **Multi-stacked silicon wire waveguides and couplers toward 3D optical interconnects  
(Invited Paper)** [8630-7]  
J. Kang, N. Nishiyama, Y. Atsumi, T. Amemiya, S. Arai, Tokyo Institute of Technology (Japan)
- 8630 0A **Board-to-board optical interconnects utilizing molded embedded 45 degree mirrors and  
print-on-demand micro-lenses as proximity vertical coupler** [8630-9]  
X. Lin, The Univ. of Texas at Austin (United States); A. Hosseini, Omega Optics, Inc. (United  
States); X. Dou, The Univ. of Texas at Austin (United States); H. Subbaraman, Omega Optics,  
Inc. (United States); R. T. Chen, The Univ. of Texas at Austin (United States)

---

**SESSION 3 NANOPHOTONICS IN OI**

---

- 8630 0C **Compact optical modulator in Si photonic crystals (Invited Paper)** [8630-11]  
T. Baba, H. C. Nguyen, Yokohama National Univ. (Japan)
- 8630 0D **2D silicon-based surface-normal vertical cavity photonic crystal waveguide array for high-density optical interconnects** [8630-12]  
J. Ahn, The Univ. of Texas at Austin (United States); H. Subbaraman, Omega Optics, Inc. (United States); L. Zhu, The Univ. of Texas at Austin (United States); S. Chakravarty, Omega Optics, Inc. (United States); E. Tutuc, R. T. Chen, The Univ. of Texas at Austin (United States)
- 8630 0E **Towards 3D plasmonic circuits: controlled coupling to multilevel plasmonic circuits** [8630-13]  
M. H. El Sherif, O. S. Ahmed, M. H. Bakr, McMaster Univ. (Canada); M. A. Swillam, American Univ. in Cairo (Egypt)

---

**SESSION 4 PARALLEL OPTICAL LINKS**

---

- 8630 0F **Optical transceivers for interconnections in satellite payloads (Invited Paper)** [8630-14]  
M. Karppinen, V. Heikkinen, E. Juntunen, K. Kautio, J. Ollila, A. Sitomaniemi, A. Tanskanen, VTT Technical Research Ctr. of Finland (Finland)
- 8630 0G **Dynamic polymer ribbon couplers for card-to-backplane optical interconnects** [8630-15]  
G. Jiang, S. Baig, M. R. Wang, Univ. of Miami (United States)

---

**SESSION 5 DATA LINKS AND OPTICAL CABLES**

---

- 8630 0J **Optics vs. copper: from the perspective of "Thunderbolt" interconnect technology (Invited Paper)** [8630-18]  
H. Cheng, C. Krause, J. Ko, M. Gao, G. Liu, H. Wu, M. Qi, C.-C. Lam, Intel Corp. (United States)
- 8630 0K **An all-silicon optical PC-to-PC link utilizing USB** [8630-19]  
M. E. Goosen, A. C. Alberts, INSiAVA (Pty) Ltd. (South Africa); P. J. Venter, M. du Plessis, Univ. of Pretoria (South Africa); P. Rademeyer, INSiAVA (Pty) Ltd. (South Africa)
- 8630 0L **Fiber optic cable-based high-resolution long-distance VGA extenders** [8630-20]  
J.-G. Rhee, I. Lee, H. Kim, S. Kim, Terawave Inc. (Korea, Republic of); Y.-W. Koh, H. Kim, FiberPro Inc. (Korea, Republic of); J. Lim, C. Kim, J. Kim, KAIST (Korea, Republic of)
- 8630 0M **Optical interconnect for large-scale systems (Invited Paper)** [8630-21]  
W. Dress, Lightfleet Corp. (United States)

---

**SESSION 6 WDM SOLUTIONS FOR OI**

---

- 8630 OP **Scalable optical transmitter and receiver based on cascaded nanoresonator modulators and multiwavelength laser** [8630-24]  
L. O'Faolain, Univ. of St. Andrews (United Kingdom) and Stanford Univ. (United States); K. Debnath, Univ. of St. Andrews (United Kingdom); F. Y. Gardes, Univ. of Surrey (United Kingdom); A. Steffan, u<sup>2</sup>t Photonics AG (Germany); E. Tasyurek, D. A. B. Miller, Stanford Univ. (United States); G. Reed, Univ. of Surrey (United Kingdom); T. F. Krauss, Univ. of St. Andrews (United Kingdom)

---

**SESSION 7 ACTIVE COMPONENTS AND DEVICES**

---

- 8630 OQ **High-power flip-chip-bonded silicon hybrid laser for temperature-control-free operation with micro-ring resonator-based modulator (Invited Paper)** [8630-26]  
S. Tanaka, S.-H. Jeong, T. Akiyama, S. Sekiguchi, T. Kurahashi, Y. Tanaka, K. Morito, Fujitsu Labs. Ltd. (Japan)

---

**SESSION 8 OPTICAL PCB**

---

- 8630 OU **Design principles and realization of electro-optical circuit boards (Invited Paper)** [8630-30]  
F. Betschon, T. Lamprecht, M. Halter, S. Beyer, vario-optics ag (Switzerland); H. Peterson, Mohagi LLC (United States)
- 8630 OW **24-ch microlens-integrated no-polish connector for optical interconnection with polymer waveguides** [8630-32]  
T. Shiraishi, T. Yagisawa, T. Ikeuchi, Fujitsu Labs. Ltd. (Japan); O. Daikuhara, Fujitsu Component Ltd. (Japan); K. Tanaka, Fujitsu Labs. Ltd. (Japan)

---

**SESSION 9 MATERIALS FOR OI**

---

- 8630 OY **Polymer-based optical interconnects using nanoimprint lithography (Invited Paper)** [8630-34]  
A. Boersma, S. Wieggersma, TNO (Netherlands); B. J. Offrein, IBM Zürich Research Lab. (Switzerland); J. Duis, TE Connectivity (Netherlands); J. Delis, Momentive Performance Materials (Netherlands); M. Ortsiefer, Vertilas (Germany); G. van Steenberge, IMEC (Belgium); M. Karppinen, VTT Technical Research Ctr. of Finland (Finland); A. van Blaaderen, Utrecht Univ. (Netherlands); B. Corbett, Tyndall National Institute (Ireland)
- 8630 OZ **Embedded planar glass waveguide optical interconnect for data centre applications (Invited Paper)** [8630-35]  
R. Pitwon, Xyratex Technology Ltd. (United Kingdom); H. Schröder, L. Brusberg, Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration (Germany); J. Graham-Jones, Plymouth Univ. (United Kingdom); K. Wang, Xyratex Technology Ltd. (United Kingdom)

- 8630 12 **Low loss polycrystalline silicon waveguides and devices for multilayer on-chip optical interconnects** [8630-38]  
D. Kwong, The Univ. of Texas at Austin (United States); A. Hosseini, Omega Optics Inc. (United States); J. Covey, Y. Zhang, X. Xu, R. T. Chen, The Univ. of Texas at Austin (United States)

---

**SESSION 10 SI PHOTONICS FOR OPTICAL INTERCONNECTS I: JOINT SESSION WITH CONFERENCES 8628 AND 8630**

---

- 8630 14 **Silicon photonics for advanced optical communication systems (Invited Paper)** [8630-40]  
Z. Zhou, X. Wang, H. Yi, Z. Tu, W. Tan, Q. Long, M. Yin, Y. Huang, Peking Univ. (China)

---

**SESSION 11 SI PHOTONICS FOR OPTICAL INTERCONNECTS II: JOINT SESSION WITH CONFERENCES 8628 AND 8630**

---

- 8630 16 **Integrated high speed hybrid silicon transmitter (Invited Paper)** [8630-42]  
S. R. Jain, Y. Tang, S. Srinivasan, M. J. R. Heck, J. E. Bowers, Univ. of California, Santa Barbara (United States)

---

**POSTER SESSION**

---

- 8630 18 **Broadband thermo-optic switch based on a W2 photonic crystal waveguide** [8630-44]  
K. Cui, X. Feng, Y. Huang, Q. Zhao, Z. Huang, W. Zhang, Tsinghua Univ. (China)
- 8630 19 **Vertically integrated double-layer on-chip crystalline silicon nanomembranes based on adhesive bonding** [8630-45]  
Y. Zhang, D. Kwong, X. Xu, The Univ. of Texas at Austin (United States); A. Hosseini, Omega Optics, Inc. (United States); S. Y. Yang, J. A. Rogers, Univ. of Illinois at Urbana-Champaign (United States); R. T. Chen, The Univ. of Texas at Austin (United States)
- 8630 1C **Subwavelength grating couplers for efficient light coupling into silicon nanomembrane based photonic devices** [8630-48]  
H. Subbaraman, Omega Optics, Inc. (United States); X. Xu, J. Covey, R. T. Chen, The Univ. of Texas at Austin (United States)

*Author Index*

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- 1 Integration Technologies I  
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- 3 Nanophotonics in OI  
**Hyo-Hoon Park**, KAIST (Korea, Republic of)
- 4 Parallel Optical Links  
**Peter Van Daele**, Universiteit Gent (Belgium)
- 5 Data Links and Optical Cables  
**Henning Schröder**, Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration (Germany)
- 6 WDM Solutions for OI  
**Ray T. Chen**, The University of Texas at Austin (United States)
- 7 Active Components and Devices  
**Michael R. Wang**, University of Miami (United States)
- 8 Optical PCB  
**Michael R. Wang**, University of Miami (United States)
- 9 Materials for OI  
**Ruth Houbertz-Krauss**, Fraunhofer-Institut für Silicatforschung (Germany)
- 10 Si Photonics for Optical Interconnects I: Joint Session with Conferences 8628 and 8630  
**Ray T. Chen**, The University of Texas at Austin (United States)
- 11 Si Photonics for Optical Interconnects II: Joint Session with Conferences 8628 and 8630  
**Louay A. Eldada**, Amprius, Inc. (United States)